

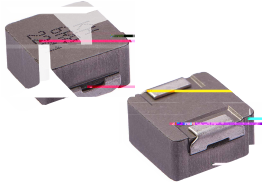
# MDA HT Series

## SMD Low Profile High Current Molded Inductor

### Size 1365

#### FEATURES

High performance realized by metal dust core and hot pressing process.

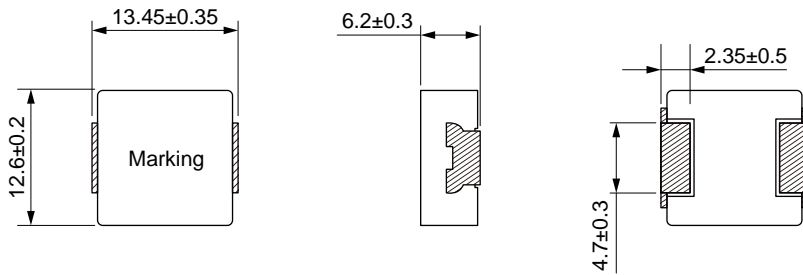


#### APPLICATION

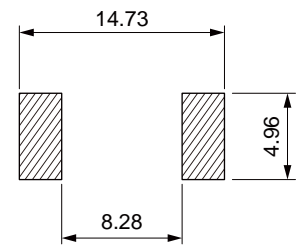
Thermal management products, such as water pumps and valves

HVAC

#### Dimensions: [mm]



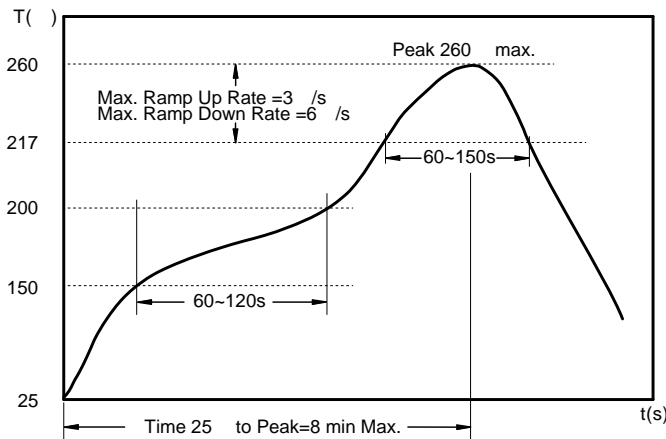
#### Land Pattern: [mm]



#### Electrical Properties:

Part No	Inductance @ 100KHz/1V	Tolerance	Temperature Rise Current Typ.	Temperature Rise Current Max.	Current Typ.	Current Max.	DC Resistance Max.
MDA1365HT-R68M	0.68	±20%	38.0	30.0	29.0	20.0	1.7
MDA1365HT-1R0M	1.00	±20%	32.0	27.5	20.0	17.0	2.1
MDA1365HT-1R5M	1.50	±20%	26.0	23.0	18.0	15.4	3.0
MDA1365HT-2R2M	2.20	±20%	21.0	18.9	17.5	15.0	4.5
MDA1365HT-3R3M	3.30	±20%	18.3	16.5	17.0	14.6	6.0
MDA1365HT-4R7M	4.70	±20%	15.0	13.5	13.5	11.6	8.7
MDA1365HT-6R8M	6.80	±20%	13.8	12.8	10.5	9.0	11.3
MDA1365HT-100M	10.0	±20%	11.0	9.9	9.2	7.9	17.2
MDA1365HT-150M	15.0	±20%	8.7	7.8	7.2	6.2	28.2
MDA1365HT-220M	22.0	±20%	7.0	6.2	6.3	5.4	40.0
MDA1365HT-330M	33.0	±20%	5.5	5.0	4.3	3.7	69.0
MDA1365HT-470M	47.0	±20%	4.2	3.8	3.8	3.3	104

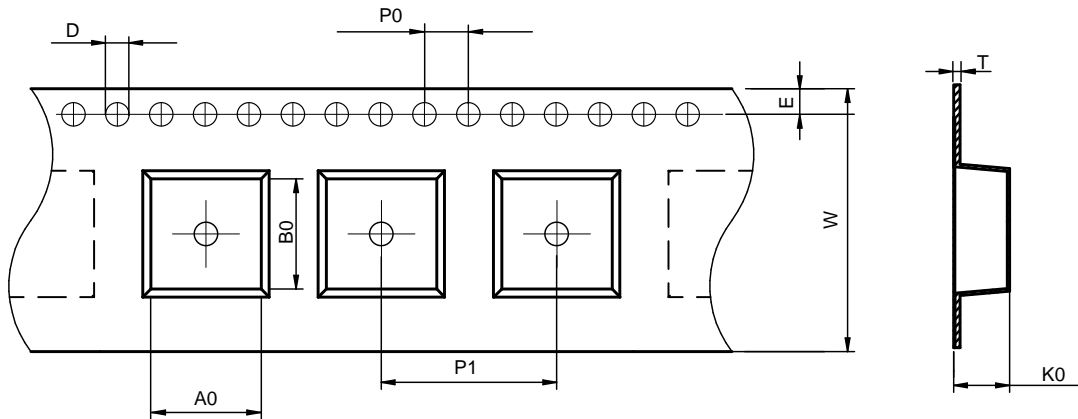
## Soldering Reflow:



Preheat condition: 150 ~200 °C / 60~120 sec.  
 Allowed time above 217 °C : 60~150 sec.  
 Max temperature: 260 °C .  
 Max time at max temperature: 30 sec.  
 Allowed Reflow time: 2x max.

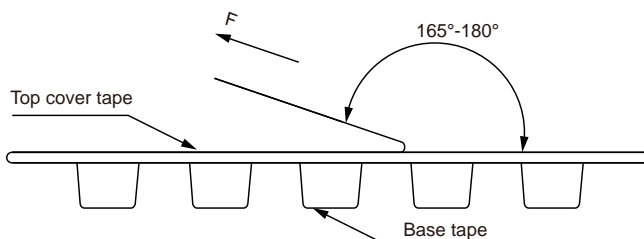
## Packaging Information:

### Tape Dimension :



Series	A0 (mm)	B0 (mm)	D (mm)	P0 (mm)	P1 (mm)	W (mm)	K0 (mm)	E (mm)	T (mm)
MDA1365HT	13.1±0.1	14.0±0.1	1.5±0.1	4.0±0.1	16±0.1	24±0.3	6.7±0.1	1.75±0.1	0.50±0.05

### Peel force of top cover tape:

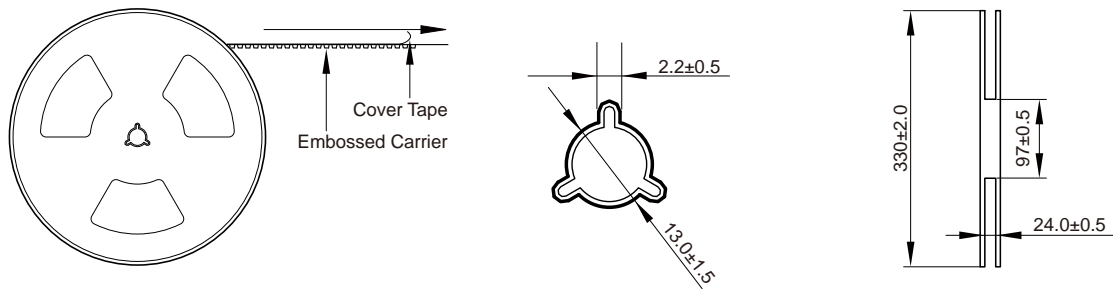


The peel force of top cover tape shall be between 0.1 to 1.3 N

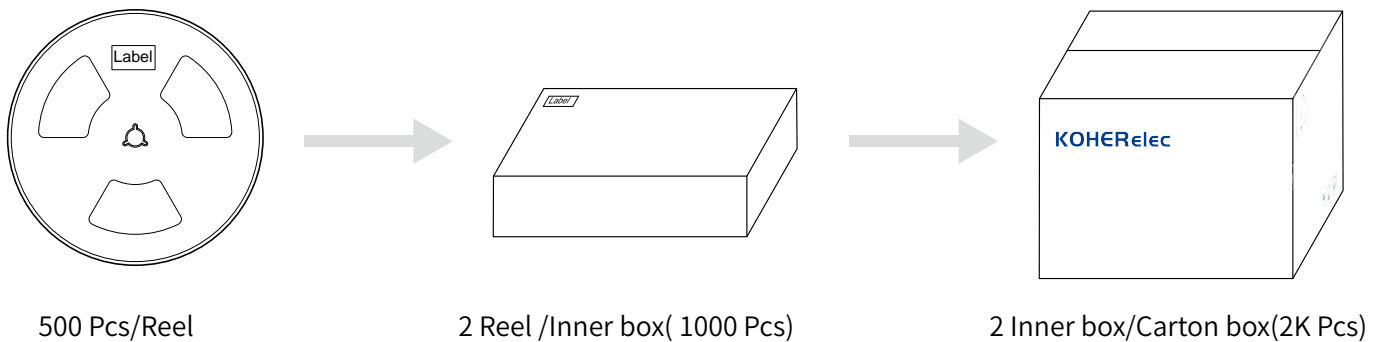
### Product Marking:

Marking	KH+Printing (Inductance+period)
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## Reel Dimension : [mm]



## Packaging Quantity:



## Cautions and Warnings:

### Storage Conditions :

- The storage period is within 12 months after the completion of production. Be sure to follow the storage conditions (temperature: -5 to 35°C, humidity: 75% RH Max).If the storage period elapses, the soldering of the terminal electrodes may deteriorate.The warranty period is one year.
- Product should not be exposed to environment with high temperature, high humidity, dust, corrosive gas and etc.
- Products should be handled with care to avoid damage or contamination from perspiration and skin oils.
- Please always handle products carefully to prevent any damage caused by dropping down or inappropriate removing.

### Operation Instructions:

- Self heating (temperature increase) occurs when the power is turned ON, so the tolerance should be sufficient for the set thermal design.
- Before soldering, be sure to preheat components.The preheating temperature should be set so that the temperature difference between the solder temperature and chip temperature does not exceed 150°C.
- Soldering corrections after mounting should be within the range of the conditions determined in the specifications.If overheated, a short circuit, performance deterioration, or lifespan shortening may occur.
- Generally, Koher might not be familiar with either customer's specific application or actual requests as customer does.As a result customer shall be responsible for checking and confirming whether Koher product with the performance described in the product specification is suitable for using in customer's particular application or not.